

Description

The IRLR2905TRPBF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

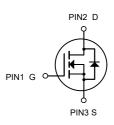


TO-252-2L

General Features

 $V_{DS} = 60V I_{D} = 30 A$

 $R_{DS(ON)}$ < 26m Ω @ V_{GS} =10V



N-Channel MOSFET

Application

Battery protection

Load switch

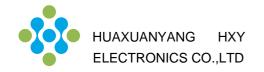
Uninterruptible power supply

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
IRLR2905TRPBF	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (T_c=25°C unless otherwise noted)

Symbol	Parameter	Rating		
V _D s	Drain-Source Voltage	60	V	
Vgs	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	15	А	
Ірм	Pulsed Drain Current ²	46	Α	
EAS	Single Pulse Avalanche Energy ³	25.5	mJ	
las	Avalanche Current	22.6	А	
P _D @T _C =25°C	Total Power Dissipation ⁴	34.7	W	
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
Reja	Thermal Resistance Junction-Ambient ¹	62	°C/W	
Rejc	Thermal Resistance Junction-Case ¹	3.6	°C/W	



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVpss	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
△BVDSS/△TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.063		V/°C
		V _{GS} =10V , I _D =15A		22	26	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =10A		30	38	mΩ
VGS(th)	Gate Threshold Voltage	V V I 050	1.2		2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.24		mV/°C
	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =25°C			1	
IDSS		V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	uA
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		17		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		3.2		Ω
Qg	Total Gate Charge (4.5V)			12.6		
Qgs	Gate-Source Charge	V _{DS} =48V , V _{GS} =4.5V , I _D =12A		3.2		nC
Q _{gd}	Gate-Drain Charge			6.3		
T _{d(on)}	Turn-On Delay Time			8		
Tr	Rise Time	V _{DD} =30V , V _{GS} =10V ,		14.2		ns
$T_{d(off)}$	Turn-Off Delay Time	R _G =3.3 ,		24.4		
T _f	Fall Time			4.6		
C _{iss}	Input Capacitance			1378		
Coss	Output Capacitance			86		pF
Crss	Reverse Transfer Capacitance			64		·
Is	Continuous Source Current ^{1,5}				23	Α
Іѕм	Pulsed Source Current ^{2,5}	─V _G =V _D =0V , Force Current			46	Α
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V

Note:

- 1.The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2\%$
- 3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=22.6A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



Typical Characteristics

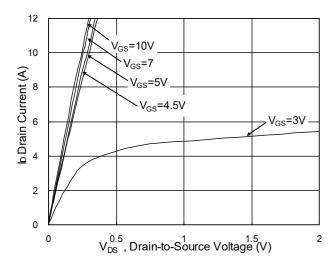


Fig.1 Typical Output Characteristics

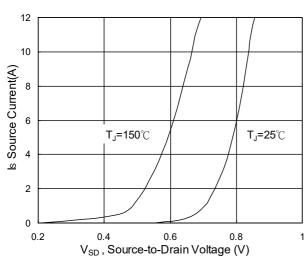


Fig.3 Forward Characteristics of Reverse

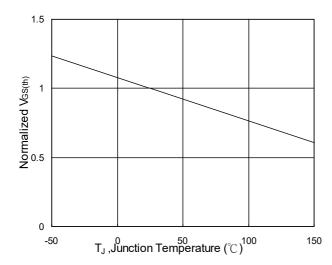


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

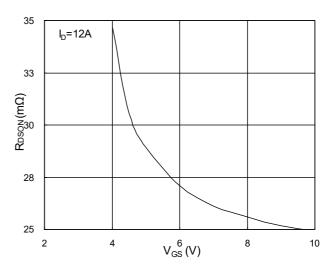


Fig.2 On-Resistance v.s Gate-Source

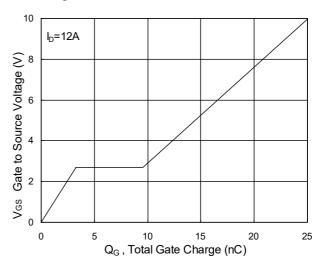


Fig.4 Gate-Charge Characteristics

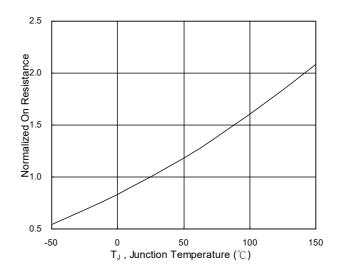
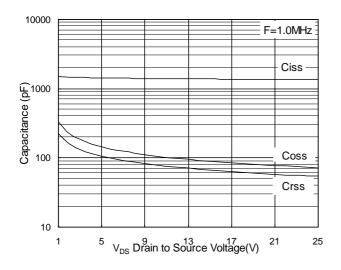


Fig.6 Normalized R_{DSON} v.s T_J



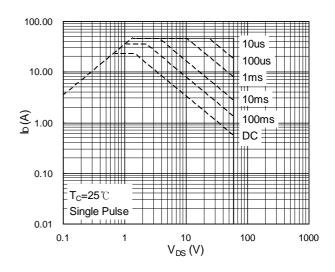


Fig.7 Capacitance

Fig.8 Safe Operating Area

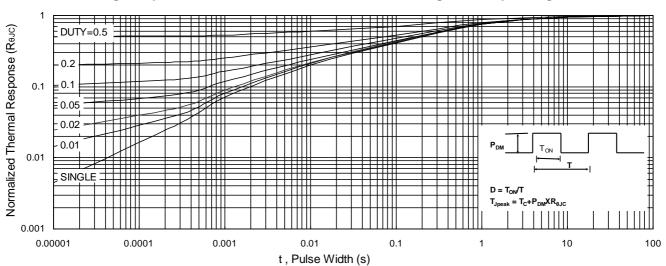


Fig.9 Normalized Maximum Transient Thermal Impedance

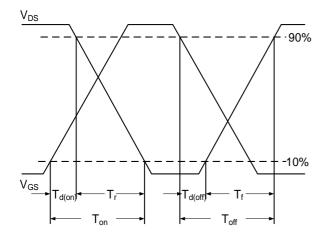


Fig.10 Switching Time Waveform

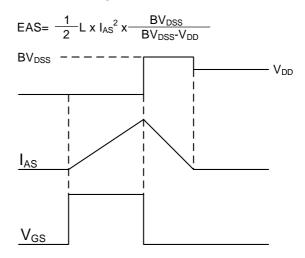
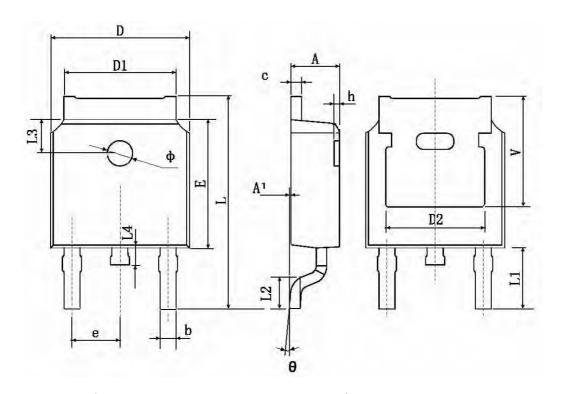


Fig.11 Unclamped Inductive Waveform

TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP. 0.211 TYP		TYP.		



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